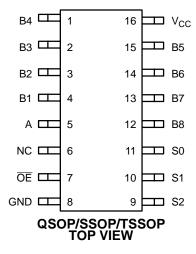
8:1 Multiplexer/ **Demultiplexer Bus Switch**

The ON Semiconductor 74FST3251 is an 8:1, high performance multiplexer/demultiplexer bus switch. The device is CMOS TTL compatible when operating between 4 and 5.5 Volts. The device exhibits extremely low R_{ON} and adds nearly zero propagation delay. The device adds no noise or ground bounce to the system.

- $R_{ON} < 4 \Omega$ Typical
- Less Than 0.25 ns-Max Delay Through Switch
- Nearly Zero Standby Current
- No Circuit Bounce
- Control Inputs are TTL/CMOS Compatible
- All Popular Packages: QSOP-16, TSSOP-16, SOIC-16



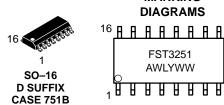
	Inp	uts		
ŌĒ	S2	S1	S0	Function
L	L	L	L	A Port = B1 Port
L	L	L	Н	A Port = B2 Port
L	L	Н	L	A Port = B3 Port
L	L	Н	Н	A Port = B4 Port
L	Н	L	L	A Port = B5 Port
L	Н	L	Н	A Port = B6 Port
L	Н	Η	L	A Port = B7 Port
L	Н	Η	Η	A Port = B8 Port
Н	Х	Х	Х	Disconnect

NOTE: H = HIGH Voltage Level, L = LOW Voltage Level, X = Don't Care



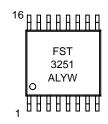
ON Semiconductor™

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TSSOP-16 **DT SUFFIX CASE 948F**



MARKING

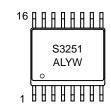
FST3251

AWLYWW

888888



QSOP-16 **QS SUFFIX CASE 492**



= Assembly Location Δ = Wafer Lot L. WL = Year W, WW = Work Week

PIN NAMES

Pin	Description
\overline{OE}_1 , \overline{OE}_2	Bus Switch Enables
S ₀ , S ₁	Select Inputs
Α	Bus A
B ₁ , B ₂ , B ₃ , B ₄	Bus B

ORDERING INFORMATION

Device	Package	Shipping
74FST3251D	SO-16	48 Units/Rail
74FST3251DR2	SO-16	2500 Units/Reel
74FST3251DT	TSSOP-16	96 Units/Rail
74FST3251DTR2	TSSOP-16	2500 Units/Reel
74FST3251QS	QSOP-16	96 Units/Rail
74FST3251QSR	QSOP-16	2500 Units/Reel

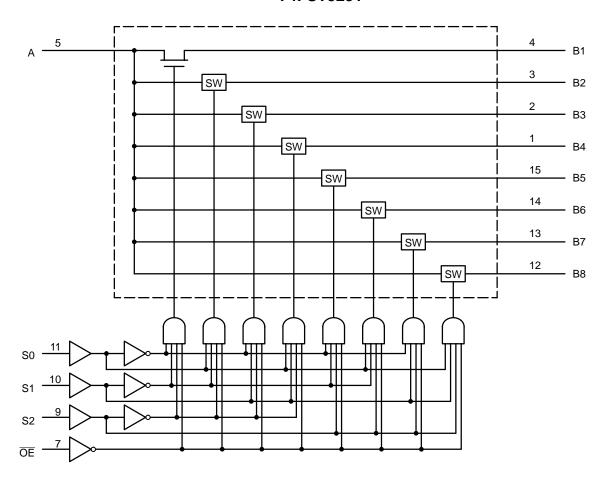


Figure 1. Logic Diagram

MAXIMUM RATINGS

Symbol	Para	ımeter	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to $+7.0$	V
VI	DC Input Voltage		-0.5 to +7.0	V
Vo	DC Output Voltage		-0.5 to +7.0	V
I _{IK}	DC Input Diode Current	V _I < GND	-50	mA
I _{OK}	DC Output Diode Current	V _O < GND	-50	mA
Io	DC Output Sink Current		128	mA
I _{CC}	DC Supply Current per Supply Pin		±100	mA
I _{GND}	DC Ground Current per Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for	10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+ 150	°C
$\theta_{\sf JA}$	Thermal Resistance	SOIC TSSOP QSOP	125 170 200	°C/W
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	>2000 >200 N/A	٧
I _{LATCH-UP}	Latch-Up Performance Ab	ove V _{CC} and Below GND at 85°C (Note 4)	±500	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum–rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

- 1. Tested to EIA/JESD22-A114-A.
- 2. Tested to EIA/JESD22-A115-A.
- 3. Tested to JESD22-C101-A.
- 4. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
V _{CC}	Supply Voltage	Operating, Data Retention Only	4.0	5.5	V
VI	Input Voltage	(Note)	0	5.5	V
Vo	Output Voltage	(HIGH or LOW State)	0	5.5	V
T _A	Operating Free–Air Temperature		-40	+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate Switch I/O	Switch Control Input $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0	DC 5	ns/V

^{5.} Unused control inputs may not be left open. All control inputs must be tied to a high or low logic input voltage level.

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			
Symbol	Parameter	Conditions	(V)	Min	Тур*	Max	Unit
V _{IK}	Clamp Diode Resistance	I _{IN} = -18mA	4.5			-1.2	V
V _{IH}	High-Level Input Voltage		4.0 to 5.5	2.0			V
V _{IL}	Low-Level Input Voltage		4.0 to 5.5			0.8	V
I _I	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	5.5			±1.0	μΑ
I _{OZ}	OFF-STATE Leakage Current	$0 \le A, B \le V_{CC}$	5.5			±1.0	μΑ
R _{ON}	Switch On Resistance (Note 6)	V _{IN} = 0 V, I _{IN} = 64 mA	4.5		4	7	Ω
		V _{IN} = 0 V, I _{IN} = 30 mA	4.5		4	7	
		V _{IN} = 2.4 V, I _{IN} = 15 mA	4.5		8	15	
		V _{IN} = 2.4 V, I _{IN} = 15 mA	4.0		11	20	
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND, I _{OUT} = 0	5.5			3	μΑ
ΔI_{CC}	Increase In I _{CC} per Input	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5			2.5	mA

AC ELECTRICAL CHARACTERISTICS

			$T_A = -40$ °C to $+85$ °C $C_L = 50$ pF, RU = RD = 500Ω				
			V _{CC} = 4	4.5–5.5 V	V _{CC} =	4.0 V	
Symbol	Parameter	Conditions	Min	Max	Min	Max	Unit
t _{PHL} , t _{PLH}	Prop Delay Bus to Bus (Note 7)	V _I = OPEN		0.25		0.25	ns
	Prop Delay, Select to Bus A		1.0	6.3		6.9	
t _{PZH} , t _{PZL}	Output Enable Time, Select to Bus B	$V_I = 7 \text{ V for } t_{PZL}$	1.0	6.0		6.5	ns
	Output Enable Time, I _{OE} to Bus A, B	V _I = OPEN for t _{PZH}	1.0	6.0		6.5	
t _{PHZ} , t _{PLZ}	Output Disable Time, Select to Bus B	$V_I = 7 \text{ V for } t_{PLZ}$	1.0	5.8		6.5	ns
	Output Disable Time, I _{OE} to Bus A, B	V _I = OPEN for t _{PHZ}	1.0	5.8		6.5	

^{7.} This parameter is guaranteed by design but is not tested. The bus switch contributes no propagation delay other than the RC delay of the typical On resistance of the switch and the 50 pF load capacitance, when driven by an ideal voltage source (zero output impedance).

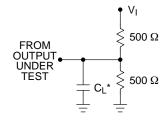
CAPACITANCE (Note 8)

Symbol	Parameter	Conditions	Тур	Max	Unit
C _{IN}	Control Pin Input Capacitance	V _{CC} = 5.0 V	3		pF
C _{I/O}	A Port Input/Output Capacitance	V_{CC} , $\overline{OE} = 5.0 \text{ V}$	13		pF
C _{I/O}	B Port Input/Output Capacitance	V _{CC} , OE = 5.0 V	5		pF

^{8.} $T_A = +25$ °C, f = 1 MHz, Capacitance is characterized but not tested.

^{*}Typical values are at V_{CC} = 5.0 V and T_A = 25°C.
6. Measured by the voltage drop between A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the two (A or B) pins.

AC Loading and Waveforms



NOTES:

- 1. Input driven by 50 Ω source terminated in 50 $\Omega.$
- 2. CL includes load and stray capacitance.
- ${}^{*}C_{L} = 50 pF$

Figure 2. AC Test Circuit

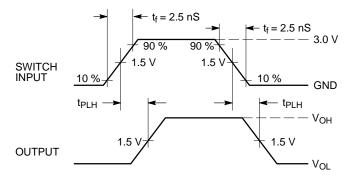


Figure 3. Propagation Delays

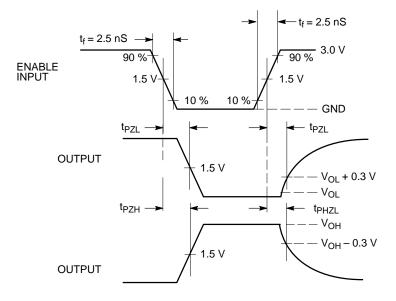
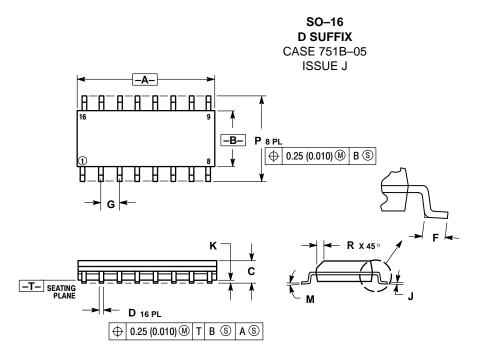


Figure 4. Enable/Disable Delays

PACKAGE DIMENSIONS



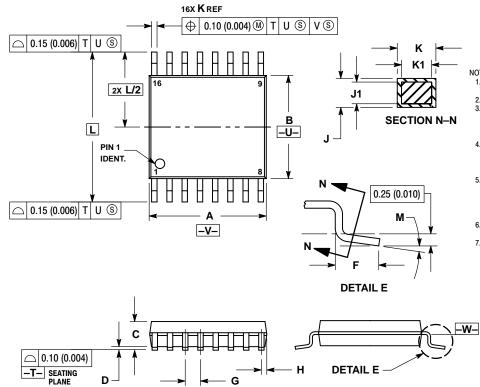
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) 3.
- PER SIDE.
- PEH SIDE.

 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7°	0°	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH.
 PROTRUSIONS OR GATE BURRS. MOLD FLASH
 OR GATE BURRS SHALL NOT EXCEED 0.15
 (0.006) PER SIDE.
- (0.006) PEH SIDE.

 JIMENSION B DOES NOT INCLUDE INTERLEAD
 FLASH OR PROTRUSION. INTERLEAD FLASH OR
 PROTRUSION SHALL NOT EXCEED
 0.25 (0.10) PEH SIDE.

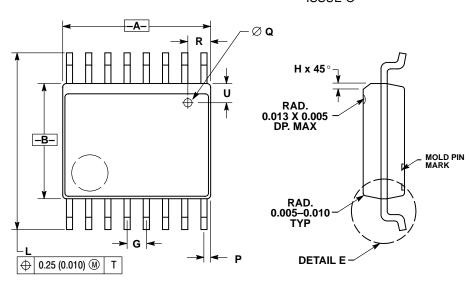
 JIMENSION K DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION. SHALLOWABLE DAMBAR
- PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

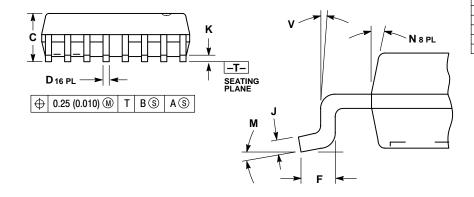
ĺ		MILLIN	IETERS	INC	HES	
	DIM	MIN	MAX	MIN	MAX	
	Α	4.90	5.10	0.193	0.200	
	В	4.30	4.50	0.169	0.177	
	С		1.20		0.047	
	D	0.05	0.15	0.002	0.006	
	F	0.50	0.75	0.020	0.030	
	G	0.65	BSC	0.026 BSC		
	Н	0.18	0.28	0.007	0.011	
	J	0.09	0.20	0.004	0.008	
	J1	0.09	0.16	0.004	0.006	
	K	0.19	0.30	0.007	0.012	
	K1	0.19	0.25	0.007	0.010	
	L	6.40		0.252		
	M	0°	8°	0°	8°	

D

PACKAGE DIMENSIONS

QSOP-16 **QS SUFFIX** CASE 492-01 ISSUE O





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. THE BOTTOM PACKAGE SHALL BE BIGGER THAN THE TOP PACKAGE BY 4 MILS (NOTE: LEAD SIDE ONLY). BOTTOM PACKAGE DIMENSION SHALL FOLLOW THE DIMENSION STATED IN THIS DRAWING.
 4. PLASTIC DIMENSIONS DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 6 MILS PER SIDE.
 5. BOTTOM EJECTOR PIN WILL INCLUDE THE
- BOTTOM EJECTOR PIN WILL INCLUDE THE COUNTRY OF ORIGIN (COO) AND MOLD CAVITY I.D.

	INC	HES	MILLIM	ETERS
DIM	MAX	MIN	MAX	MIN
Α	0.189	0.196	4.80	4.98
В	0.150	0.157	3.81	3.99
С	0.061	0.068	1.55	1.73
D	0.008	0.012	0.20	0.31
F	0.016	0.035	0.41	0.89
G	0.025	BSC	0.64	BSC
Н	0.008	0.018	0.20	0.46
J	0.0098	0.0075	0.249	0.191
K	0.004	0.010	0.10	0.25
L	0.230	0.244	5.84	6.20
M	0°	8°	0 °	8°
N	0°	7°	0°	7°
Р	0.007	0.011	0.18	0.28
Q	0.020	DIA	0.51	DIA
R	0.025	0.035	0.64	0.89
U	0.025	0.035	0.64	0.89
٧	0°	8°	0°	8°

DETAIL E

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